CHEMTRONICS® Technical Data Sheet

TDS # SWick

Soder-Wick® Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick® offers the state of the art in desoldering technology. Soder-Wick® is designed for today's heat sensitive electronic components using lighter mass, pure copper braid construction that allows for better thermal conductivity, even at low temperatures. Soder-Wick® responds faster than conventional desoldering braids thereby minimizing overheating and preventing PCB damage. A full range of sizes and flux types are available, including Rosin, No Clean, unfluxed and a high temperature Lead-Free version. Whatever the requirement, Soder-Wick® has the answer.

- Requires little or no post solder cleaning
- No corrosive residues
- Optimized construction for faster wicking and heat transfer
- Halide free
- Minimizes the risk of heat damage to components and circuit boards

TYPICAL APPLICATIONS

Soder-Wick® desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Flux Types: Rosin Grade WW, Type "R"

Patented No Clean High Temperature No Clean

Specifications: ANSI/IPC J STD-004

MIL-F-14256 F

No Clean Flux Spec: MIL-STD-883B

Bellcore TR-NWT-000078

ANSI/IPC J SF818

Shelflife: 2 years

RoHS/WEEE

Status



| Size# | Width Inches | Color | Width Metric |
|-------|-----------------|--------|-----------------|
| 1 | .030" | White | 0.8mm |
| 2 | .060" | Yellow | 1.5mm |
| 3 | .080" | Green | 2.0mm |
| 4 | .110" | Blue | 2.8mm |
| 5 | .145" | Brown | 3.7mm |
| 6 | .210" | Red | 5.3mm |
| BGA | - | Purple | - |

STATIC DISSIPATIVE PACKAGING

Soder-Wick[®] SD is packaged on Static Dissipative bobbins in 5 and 10-foot lengths to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B, and meet the static delay rate provision of MIL-B-81705C.

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick[®] desoldering braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F
- 4) Place wick on solder joint and place tip of hot iron on top of wick
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from solder joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard the used portion of the wick.
- 9) If needed, clean PCB with CircuitWorks® Flux Remover Pen and remove soils with a ControlWipes™ absorbent wipe.

SODER-WICK® IS DESIGNED TO MEET OR EXCEED THE FOLLOWING:

MIL-F-14256F, Type R NASA-STD-8739.3 DOD-STD-883E, Method 2022 ANSI/IPC J STD-004, Type ROL0 BELLCORE TR-NWT-000078 ANSI/IPC J SF-818

SODER-WICK® SD BOBBINS ARE DESIGNED TO MEET OR EXCEED:

MIL-STD-2000A MIL-B-81705C MIL-STD-1686C MIL-HDBK-263B

TECHNICAL & APPLICATION ASSISTANCE

Chemtronics® provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

AVAILABILITY

Series:

- 40 Soder-Wick® Lead-Free, SD Bobbin
- 50 Soder-Wick[®] Rosin
- 80 Soder-Wick® Rosin, SD Bobbin
- **60** Soder-Wick[®] No Clean, SD Bobbin
- **70** Soder-Wick[®] Unfluxed
- 75 Soder-Wick® Unfluxed, SD Bobbin

VacuPak[™] Packaging

The VacuPak Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

HELPFUL HINTS:

Water Soluble Users: Use Soder-Wick® Unfluxed **70** or **75** Series to dip in water soluble flux and then desolder normally.

Ball Grid Array: Use Soder-Wick[®] BGA with a large tipped iron to remove solder from a number of BGA pads all at once.

NOTE: This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. ITW CHEMTRONICS® does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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MANUFACTURED BY:

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REV. F (06/06)



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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